

## PSMN4R0-30YL

# N-channel 30 V 4 m $\Omega$ logic level MOSFET in LFPAK

Rev. 04 — 10 March 2011

**Product data sheet** 

## 1. Product profile

### 1.1 General description

Logic level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product is designed and qualified for use in industrial and communications applications.

### 1.2 Features and benefits

- High efficiency due to low switching and conduction losses
- Suitable for logic level gate drive sources

## 1.3 Applications

- Class-D amplifiers
- DC-to-DC converters

- Motor control
- Server power supplies

### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{DS}$	drain-source voltage	$T_j \ge 25 \text{ °C}; T_j \le 175 \text{ °C}$	-	-	30	V
I <sub>D</sub>	drain current	$T_{mb}$ = 25 °C; $V_{GS}$ = 10 V; see <u>Figure 1</u>	-	-	100	Α
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; see Figure 2	-	-	69	W
T <sub>j</sub>	junction temperature		-55	-	175	°C
Static chara	acteristics					
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 15 \text{ A};$ $T_j = 25 \text{ °C}$	-	2.72	4	mΩ
Dynamic ch	naracteristics					
$Q_{GD}$	gate-drain charge	$V_{GS} = 4.5 \text{ V}; I_D = 10 \text{ A};$	-	4.3	-	nC
Q <sub>G(tot)</sub>	total gate charge	V <sub>DS</sub> = 12 V; see <u>Figure 14</u> ; see <u>Figure 15</u>	-	17.6	-	nC
Avalanche ruggedness						
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	$\begin{split} &V_{GS}=10 \text{ V; } T_{j(init)}=25 \text{ °C;} \\ &I_D=99 \text{ A; } V_{sup} \leq 30 \text{ V;} \\ &R_{GS}=50  \Omega; \text{ unclamped} \end{split}$	-	-	41	mJ



## 2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source		
2	S	source	mb	D D
3	S	source		
4	G	gate	[q]	
mb	D	mounting base; connected to drain	1 2 3 4	mbb076 S
			SOT669 (LFPAK)	

## 3. Ordering information

Table 3. Ordering information

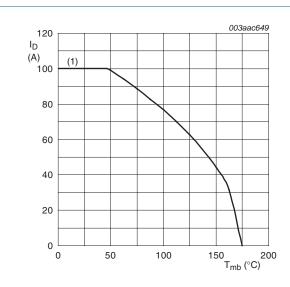
Type number	Package		
	Name	Description	Version
PSMN4R0-30YL	LFPAK	plastic single-ended surface-mounted package (LFPAK); 4 leads	SOT669

## 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage	T <sub>j</sub> ≥ 25 °C; T <sub>j</sub> ≤ 175 °C	-	30	V
$V_{DSM}$	peak drain-source voltage	$t_p \le 25 \text{ ns}; f \le 500 \text{ kHz}; E_{DS(AL)} \le 160 \text{ nJ};$ pulsed	-	35	V
$V_{DGR}$	drain-gate voltage	$T_j \ge 25 \text{ °C}; T_j \le 175 \text{ °C}; R_{GS} = 20 \text{ k}\Omega$	-	30	٧
$V_{GS}$	gate-source voltage		-20	20	٧
I <sub>D</sub>	drain current	$V_{GS} = 10 \text{ V}; T_{mb} = 100 \text{ °C}; \text{see } \frac{\text{Figure 1}}{\text{Model}}$	-	76	Α
		$V_{GS} = 10 \text{ V}; T_{mb} = 25 \text{ °C}; \text{ see } \frac{\text{Figure 1}}{\text{Model}}$	-	100	Α
I <sub>DM</sub>	peak drain current	pulsed; $t_p \le 10 \mu s$ ; $T_{mb} = 25 \text{ °C}$ ; see Figure 3	-	396	Α
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; see <u>Figure 2</u>	-	69	W
T <sub>stg</sub>	storage temperature		-55	175	°C
Tj	junction temperature		-55	175	°C
Source-drain	n diode				
Is	source current	T <sub>mb</sub> = 25 °C	-	99	Α
I <sub>SM</sub>	peak source current	pulsed; $t_p \le 10 \mu s$ ; $T_{mb} = 25  ^{\circ}C$	-	396	Α
Avalanche r	uggedness				
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	$V_{GS}$ = 10 V; $T_{j(init)}$ = 25 °C; $I_{D}$ = 99 A; $V_{sup}$ ≤ 30 V; $R_{GS}$ = 50 Ω; unclamped	-	41	mJ



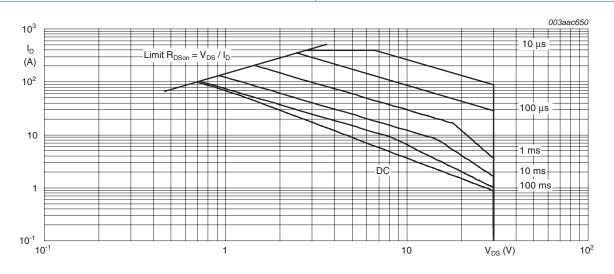
 $V_{GS} \ge 10 \mathrm{V}$ ; (1) Capped at 100 A due to package.

120 P<sub>der</sub> (%) 80 40 0 150 T<sub>mb</sub> (°C)

 $P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$ 

Continuous drain current as a function of Fig 1. mounting base temperature

Fig 2. Normalized total power dissipation as a function of mounting base temperature



 $T_{mb} = 25 \,^{\circ}C; I_{DM}$ is single pulse

Safe operating area; continuous and peak drain currents as a function of drain-source voltage

## 5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 4	-	1	1.82	K/W

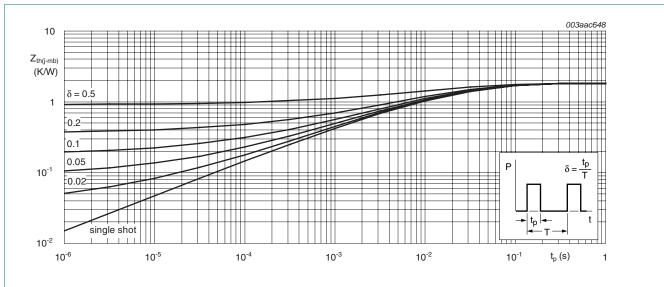


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 6. Characteristics

**Table 6. Characteristics** 

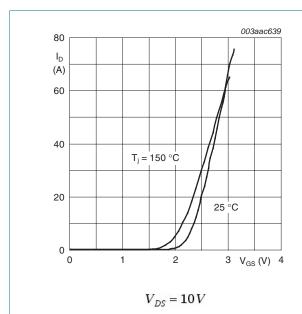
Tested to JEDEC standards where applicable.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	cteristics					
V <sub>(BR)DSS</sub>	drain-source breakdown	$I_D = 250 \ \mu A; \ V_{GS} = 0 \ V; \ T_j = 25 \ ^{\circ}C$	30	-	-	V
	voltage	$I_D = 250 \ \mu A; \ V_{GS} = 0 \ V; \ T_j = -55 \ ^{\circ}C$	27	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1$ mA; $V_{DS} = V_{GS}$ ; $T_j = 25$ °C; see <u>Figure 11</u> ; see <u>Figure 12</u>	1.3	1.7	2.15	V
		$I_D = 1$ mA; $V_{DS} = V_{GS}$ ; $T_j = 150$ °C; see <u>Figure 12</u>	0.65	-	-	V
		$I_D = 1$ mA; $V_{DS} = V_{GS}$ ; $T_j = -55$ °C; see <u>Figure 12</u>	-	-	2.45	V
I <sub>DSS</sub>	drain leakage current	$V_{DS} = 30 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	-	1	μΑ
		$V_{DS} = 30 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 150 \text{ °C}$	-	-	100	μΑ
$I_{GSS}$	gate leakage current	$V_{GS} = 16 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	-	100	nΑ
		$V_{GS} = -16 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	-	100	nΑ
$R_{DSon}$	drain-source on-state	$V_{GS} = 4.5 \text{ V}; I_D = 15 \text{ A}; T_j = 25 \text{ °C}$	-	3.73	5.25	$m\Omega$
	resistance	$V_{GS} = 10 \text{ V}; I_D = 15 \text{ A}; T_j = 150 \text{ °C};$ see <u>Figure 13</u>	-	-	7	mΩ
		$V_{GS} = 10 \text{ V}; I_D = 15 \text{ A}; T_j = 25 \text{ °C}$	-	2.72	4	mΩ
$R_G$	gate resistance	f = 1 MHz	-	0.52	1.5	Ω
Dynamic ch	aracteristics					
Q <sub>G(tot)</sub> total g	total gate charge	$I_D = 10 \text{ A}$ ; $V_{DS} = 12 \text{ V}$ ; $V_{GS} = 10 \text{ V}$ ; see <u>Figure 14</u> ; see <u>Figure 15</u>	-	36.6	-	nC
		$I_D = 10 \text{ A}$ ; $V_{DS} = 12 \text{ V}$ ; $V_{GS} = 4.5 \text{ V}$ ; see <u>Figure 14</u> ; see <u>Figure 15</u>	-	17.6	-	nC
		$I_D = 0 A; V_{DS} = 0 V; V_{GS} = 10 V$	-	33	-	nC
$Q_{GS}$	gate-source charge	$I_D = 10 \text{ A}; V_{DS} = 12 \text{ V}; V_{GS} = 4.5 \text{ V};$	-	5.6	-	nC
Q <sub>GS(th)</sub>	pre-threshold gate-source charge	see <u>Figure 14</u> ; see <u>Figure 15</u>	-	3.6	-	nC
Q <sub>GS(th-pl)</sub>	post-threshold gate-source charge		-	2	-	nC
$Q_{GD}$	gate-drain charge		-	4.3	-	nC
$V_{GS(pl)}$	gate-source plateau voltage	V <sub>DS</sub> = 12 V; see <u>Figure 14</u> ; see <u>Figure 15</u>	-	2.3	-	V
C <sub>iss</sub>	input capacitance	$V_{DS} = 12 V; V_{GS} = 0 V; f = 1 MHz;$	-	2090	-	pF
C <sub>oss</sub>	output capacitance	T <sub>j</sub> = 25 °C; see <u>Figure 16</u>	-	469	-	pF
C <sub>rss</sub>	reverse transfer capacitance		-	227	-	pF
t <sub>d(on)</sub>	turn-on delay time	$V_{DS} = 12 \text{ V}; R_L = 0.5 \Omega; V_{GS} = 4.5 \text{ V};$	-	28	-	ns
t <sub>r</sub>	rise time	$R_{G(ext)} = 4.7 \Omega$	-	51	-	ns
$t_{d(off)}$	turn-off delay time		-	44	-	ns
t <sub>f</sub>	fall time		-	18	-	ns

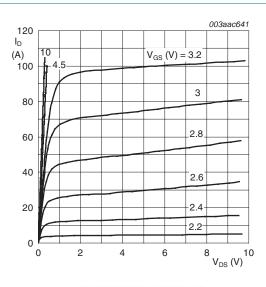
**Characteristics** ...continued Table 6.

Tested to JEDEC standards where applicable.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Source-drai	n diode					
$V_{SD}$	source-drain voltage	$I_S = 25 \text{ A}$ ; $V_{GS} = 0 \text{ V}$ ; $T_j = 25 \text{ °C}$ ; see Figure 17	-	0.83	1.2	V
t <sub>rr</sub>	reverse recovery time	$I_S = 20 \text{ A}$ ; $dI_S/dt = -100 \text{ A}/\mu s$ ;	-	39	-	ns
Q <sub>r</sub>	recovered charge	$V_{GS} = 0 \text{ V}; V_{DS} = 20 \text{ V}$	-	36	-	nC

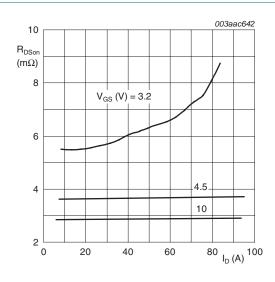


Transfer characteristics: drain current as a Fig 5. function of gate-source voltage; typical values



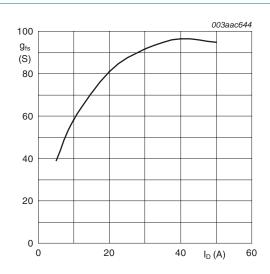
$$T_j = 25 \,^{\circ}C; t_p = 300 \,\mu s$$

Fig 6. Output characteristics: drain current as a function of drain-source voltage; typical values



Drain-source on-state resistance as a function Fig 7. of drain current; typical values

 $T_j = 25 \,^{\circ}C; t_p = 300 \mu s$ 



 $T_j=25\,^{\circ}C; V_{DS}=15\,V$ 

Forward transconductance as a function of Fig 8. drain current; typical values

PSMN4R0-30YL

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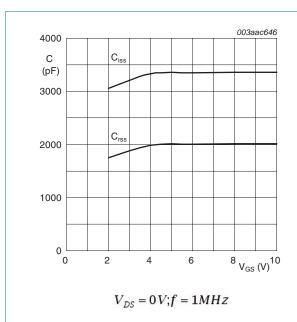


Fig 9. Input and reverse transfer capacitances as a function of gate-source voltage; typical values

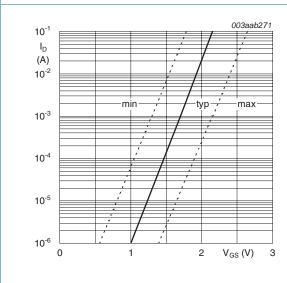
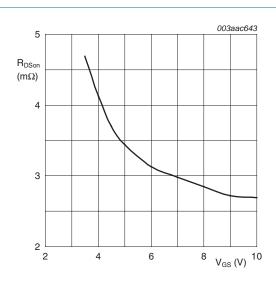


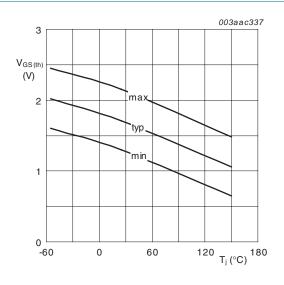
Fig 11. Sub-threshold drain current as a function of gate-source voltage

 $T_j = 25 \,^{\circ}C; V_{DS} = 5V$ 



 $T_j = 25 \,^{\circ}C; I_D = 15A$ 

Fig 10. Drain-source on-state resistance as a function of gate-source voltage; typical values



 $I_D = 1mA; V_{DS} = V_{GS}$ 

Fig 12. Gate-source threshold voltage as a function of junction temperature

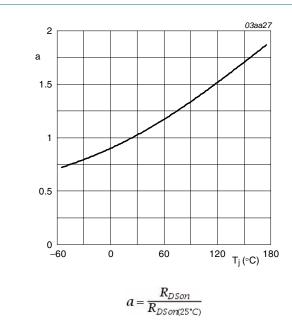


Fig 13. Normalized drain-source on-state resistance factor as a function of junction temperature

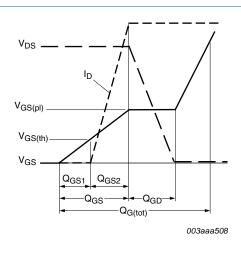


Fig 14. Gate charge waveform definitions

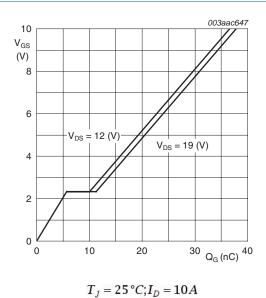
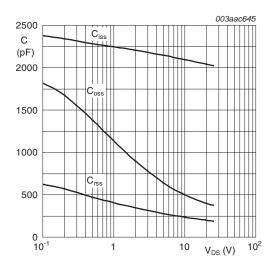


Fig 15. Gate-source voltage as a function of gate charge; typical values



 $V_{GS} = 0V; f = 1MHz$ 

Fig 16. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

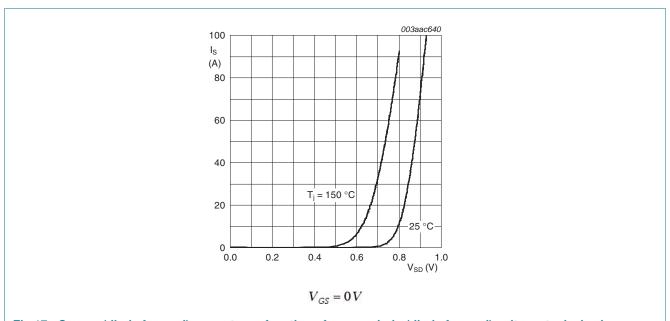
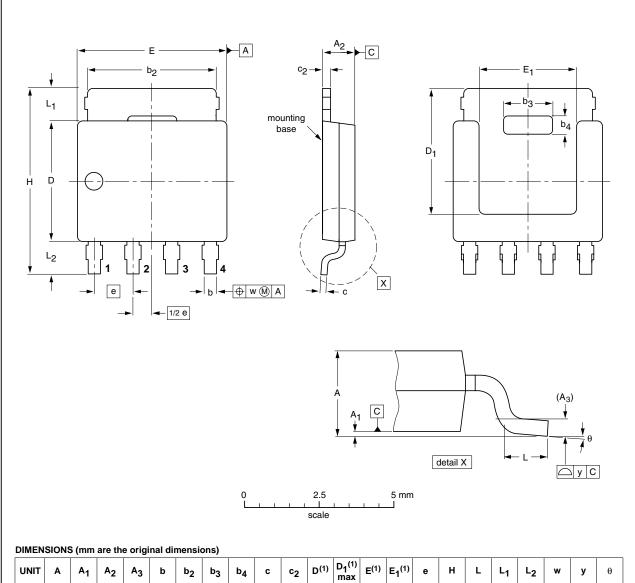


Fig 17. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values

## 7. Package outline

# Plastic single-ended surface-mounted package (LFPAK); 4 leads

**SOT669** 



#### Note

1.20 0.15 1.10

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

0.50 4.41

0.35 3.62

0.9

0.25 0.30

0.19 0.24

OUTLINE		REFER	ENCES	EUROPEAN ISSUE DA		
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE	
SOT669		MO-235		$ \  \   \bigoplus  \  \   \bigoplus$	<del>04-10-13</del> 06-03-16	

4.10

Fig 18. Package outline SOT669 (LFPAK)

PSMN4R0-30YL

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0.25

0.85

## 8. Revision history

### Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PSMN4R0-30YL v.4	20110310	Product data sheet	-	PSMN4R0-30YL v.3
Modifications:	<ul> <li>Various change</li> </ul>	es to content.		
PSMN4R0-30YL v.3	20091231	Product data sheet	-	PSMN4R0-30YL v.2

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Document status [1] [2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
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### N-channel 30 V 4 mΩ logic level MOSFET in LFPAK

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# PSMN4R0-30YL

## **Nexperia**

N-channel 30 V 4 m $\Omega$  logic level MOSFET in LFPAK

## 11. Contents

1	Product profile
1.1	General description
1.2	Features and benefits
1.3	Applications
1.4	Quick reference data1
2	Pinning information
3	Ordering information
4	Limiting values
5	Thermal characteristics4
6	Characteristics
7	Package outline10
8	Revision history11
9	Legal information12
9.1	Data sheet status
9.2	Definitions12
9.3	Disclaimers
9.4	Trademarks13
10	Contact information